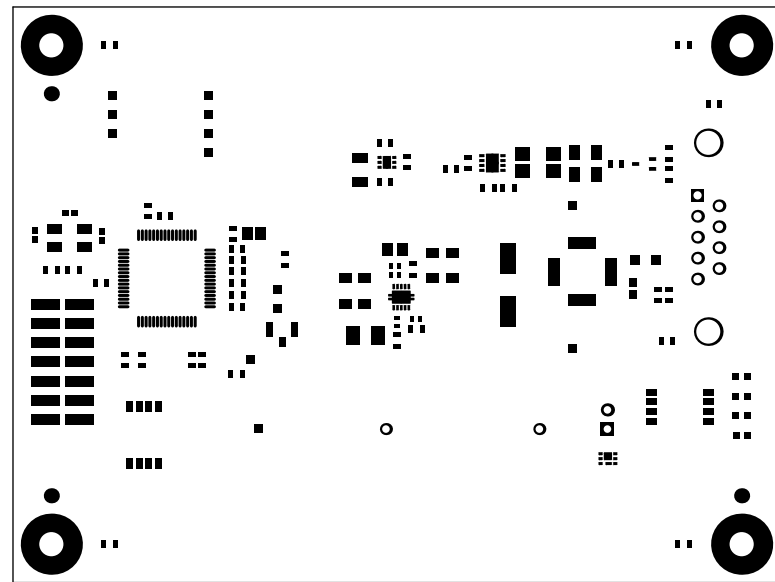
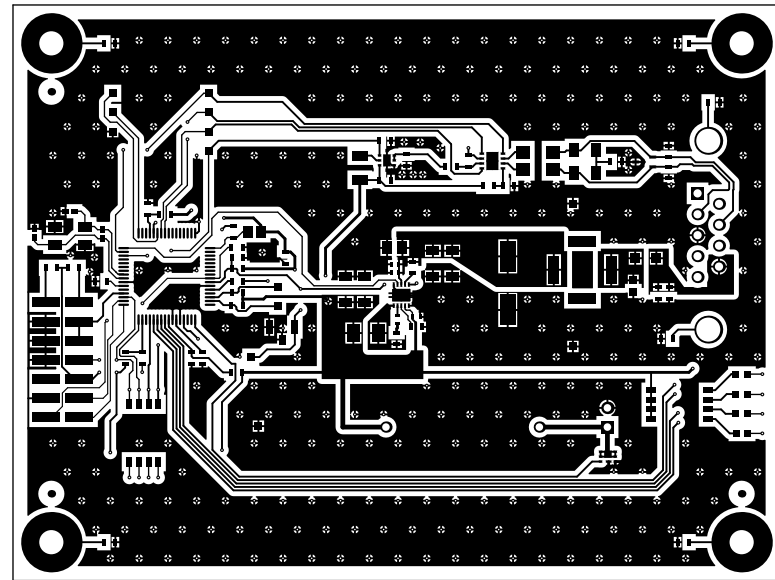


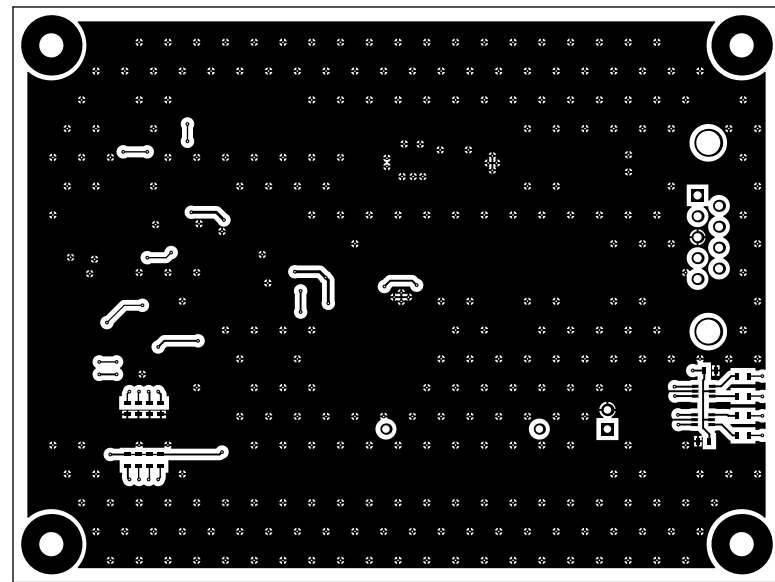
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01428		
PLOT NAME = Top Overlay	GENERATED : 6/30/2017 6:17:54 PM	TEXAS INSTRUMENTS	



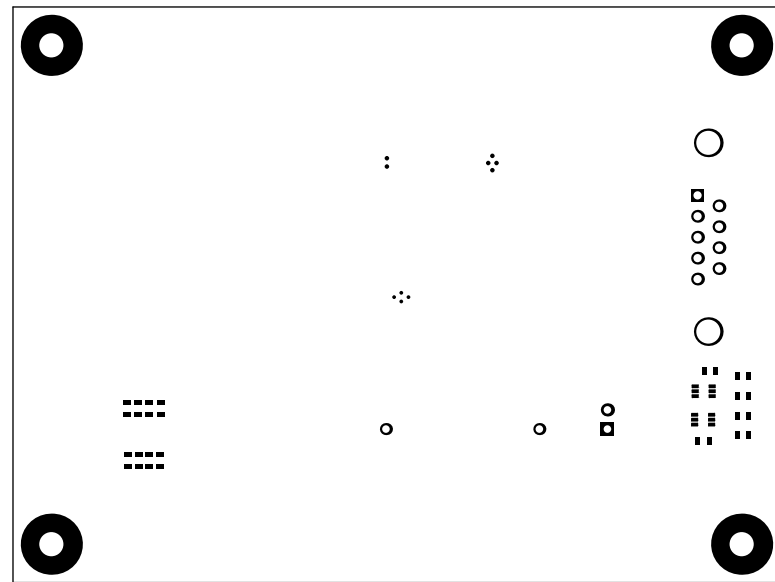
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01428		
PLOT NAME = Top Solder Mask	GENERATED : 6/30/2017 6:17:55 PM	TEXAS INSTRUMENTS	



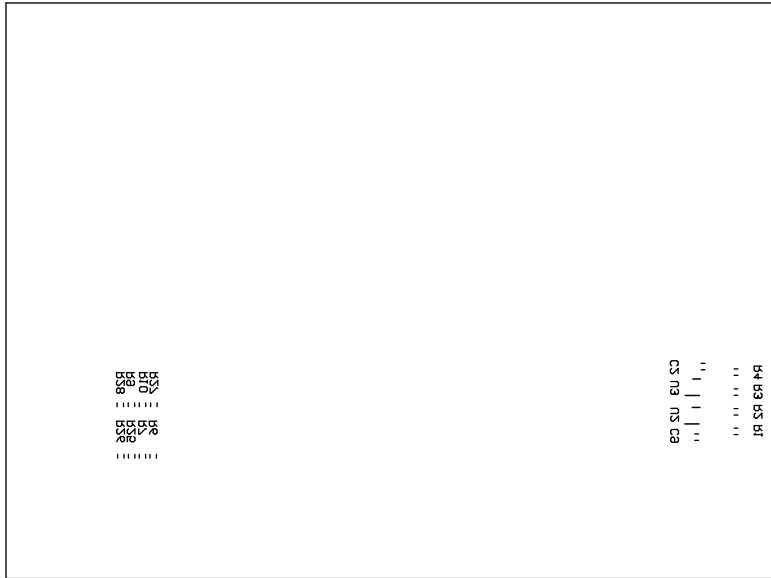
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01428		
PLOT NAME = Top Layer	GENERATED : 6/30/2017 6:17:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01428		
PLOT NAME = Bottom Layer	GENERATED : 6/30/2017 6:17:57 PM	TEXAS INSTRUMENTS	

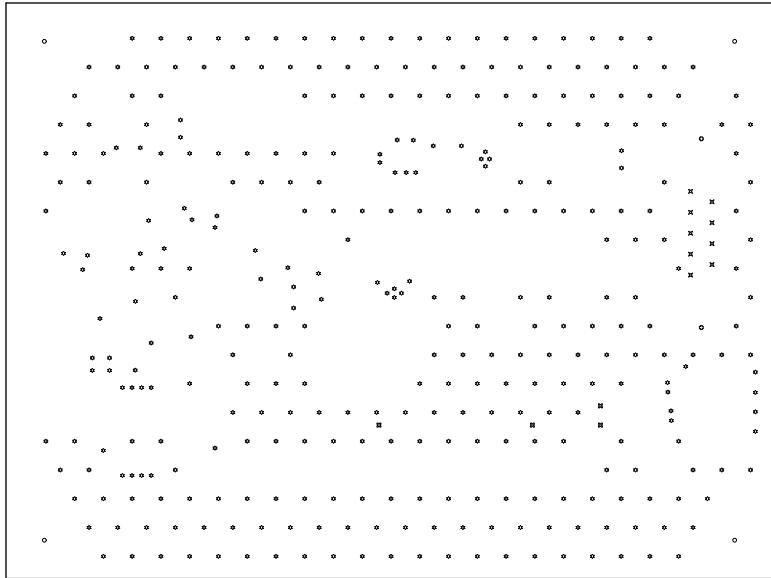


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01428		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/30/2017 6:17:58 PM	TEXAS INSTRUMENTS	

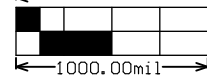
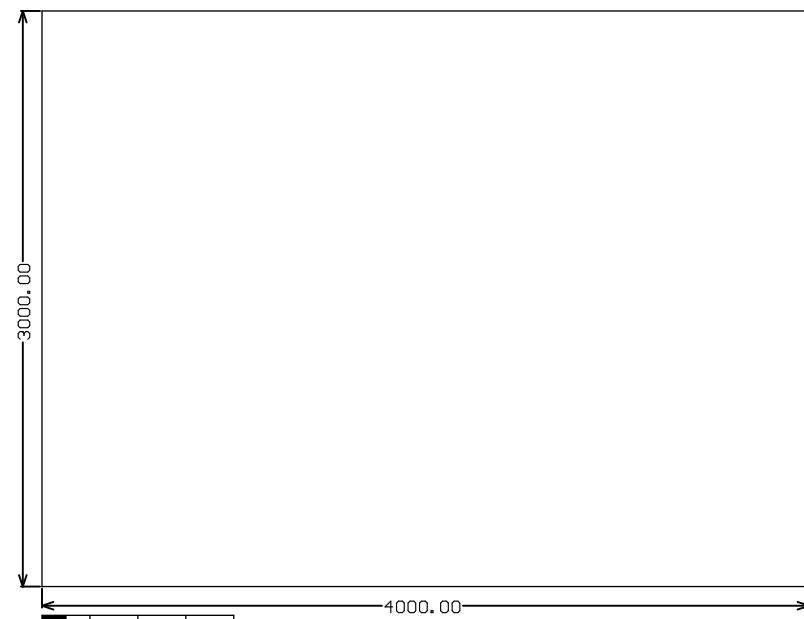


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01428		
PLOT NAME = Bottom Overlay	GENERATED : 6/30/2017 6:17:59 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
☆	338	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	9	42.91mil (1.090mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	125.20mil (3.180mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	357 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01428		
PLOT NAME = Drill Drawing	GENERATED : 6/30/2017	6:18:00 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01428	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01428		
PLOT NAME = Board Dimensions	GENERATED : 6/30/2017 6:18:01 PM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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